

In the Claims

Claim 1 (original): A semiconductor package comprising a solder having an alpha flux of less than $0.001 \text{ cts/cm}^2/\text{hr}$.

Claim 2 (original): The semiconductor package of claim 1 wherein the solder predominately comprises Ag, Bi, Cu, In, Pb or Sn.

Claim 3 (original): The semiconductor package of claim 1 wherein the solder predominately comprises Ag.

Claim 4 (original): The semiconductor package of claim 1 wherein the solder predominately comprises Sn.

Claim 5 (original): The semiconductor package of claim 1 wherein the solder is substantially lead-free.

Claim 6 (original): The semiconductor package of claim 1 wherein the solder is lead-containing solder that is at least 99 weight% lead.

Claim 7 (original): The semiconductor package of claim 6 wherein the lead-containing solder has an alpha flux of less than $0.0005 \text{ cts/cm}^2/\text{hr}$.

Claim 8 (original): The semiconductor package of claim 6 wherein the lead-containing solder has an alpha flux of less than $0.0002 \text{ cts/cm}^2/\text{hr}$.

Claim 9 (original): The semiconductor package of claim 6 wherein the lead-containing solder has an alpha flux of less than $0.0001 \text{ cts/cm}^2/\text{hr}$.

Claims 10-29 (canceled).